

Travelling Merchant: _____

DATASHEET

Standard: DP7V25000003

| Plot | | | The Label |
|------------------|---------|----------|------------------------|
| Drew | Audited | Approved | Stamp, please! Thanks! |
| | | | |
| Date: 2018.03.16 | | | |

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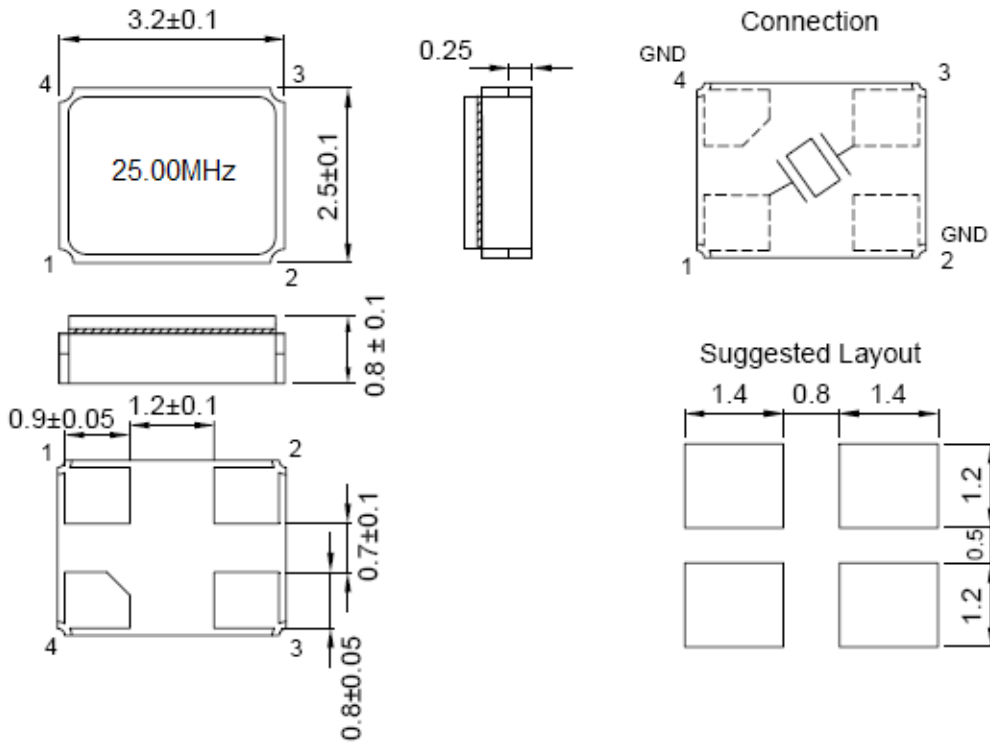
1、Electrical Parameters

| MODEL: DP7V2500003 | | | | | | | |
|--------------------|-----------------------------|--|------------------|------|------|--|--|
| No. | Parameters | SYM. | Electrical Spec. | | | | Notes |
| | | | Min. | Typ. | Max. | Units | |
| 1 | Nominal Frequency | FL | 25.00 | | | MHz | |
| 2 | Oscillation Mode | - | Fundamental | | | | |
| 3 | Load Capacitance | CL | 20 | | | pF | |
| 4 | Frequency Tolerance | - | -10 | | +10 | ppm | at 25°C ± 3°C |
| 5 | Frequency Stability | - | -30 | | +30 | ppm | Over Operating Temp. Range (Reference 25°C) |
| 6 | Operating Temperature Range | - | -40 | ~ | +85 | °C | |
| 7 | Aging | - | -3 | | +3 | ppm | 1st Year |
| 8 | Drive Level | DL | - | | 100 | uW | |
| 9 | Series Resonant Resistance | Rr | - | - | 40 | Ω | |
| 10 | Shunt Capacitance | C0 | - | - | 7 | pF | |
| 11 | Insulation Resistance | - | 500 | - | - | MΩ | at DC 100V |
| 12 | Storage Temperature Range | - | -55 | ~ | +125 | °C | |
| 13 | Drop Test | 100 cm height, 3 times on concrete floor. | | | | | JIS C6701 |
| 14 | Mechanical Shock | Device are shocked to half sine wave (1000 G) three mutually. perpendicular axes each 3 times. 0 | | | | | MIL-STD-202F |
| 15 | Vibration | Frequency range 10 ~ 2000 Hz Amplitude 1.52 mm/20G Sweep time 20 minute perpendicular axes each test time 4 hours (Total test time 12 hours) | | | | MIL-STD-883E | |
| 16 | SOLDERABILITY | MIL-STD-20E Method 208C Temperature Material Immersion depth Immersion time Flux | | | | 245±°C H63A(Silver 2~3%) 0.5 mm minimum 3±0.5 seconds Rosin resin methyl Alcohol solvent(1:4) | |



| | | |
|----|--------------------------------|---|
| 17 | RESISTANCE TO SOLDDDERING HEAT | MIL-SLD-202, Method 210, Condition I or J10 sec immersion 260 ±5°C solder pot, above 180°C is 90~120 sec. |
| 18 | LOW TEMP.STORAGE | Leave at -55°C ±2°C for 1000±12 hours |
| 19 | HIGHT TEMP.STORAGE | Leave at -125°C ±2°C for 1000±12 hours |
| 20 | THERMAL SHOCK | Total 100cycles of the flowing temperature cycle |

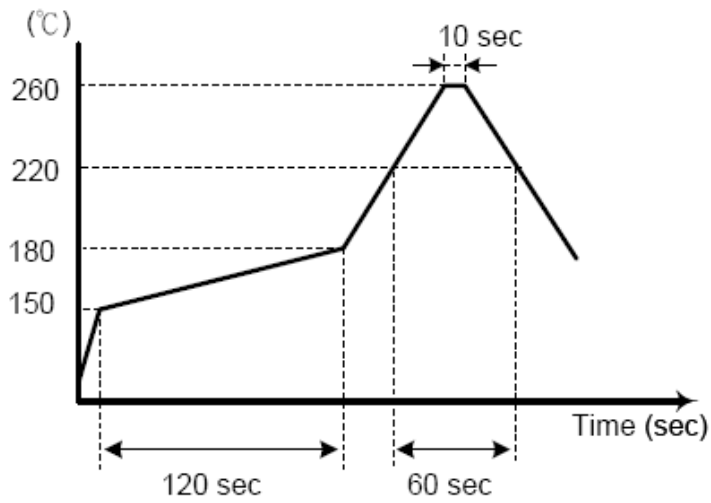
2、Mechanical Structure(mm)



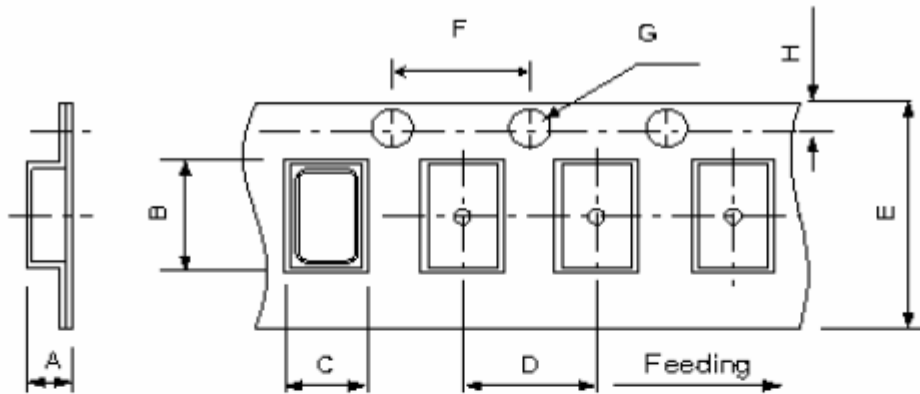
*Coplanarity of solderable areas Camber 0.10 mm Max



3、 Reflow Soldering Curve (RoHS)



4、 Package: Tape & Reel (mm)



| DIMENSIONS | A | B | C | D | E | F | G | H | (UNIT : mm) |
|------------|------|------|------|------|------|------|------|------|-------------|
| | 1.40 | 3.40 | 2.70 | 4.00 | 8.00 | 4.00 | 1.50 | 1.75 | |

REMARK :

